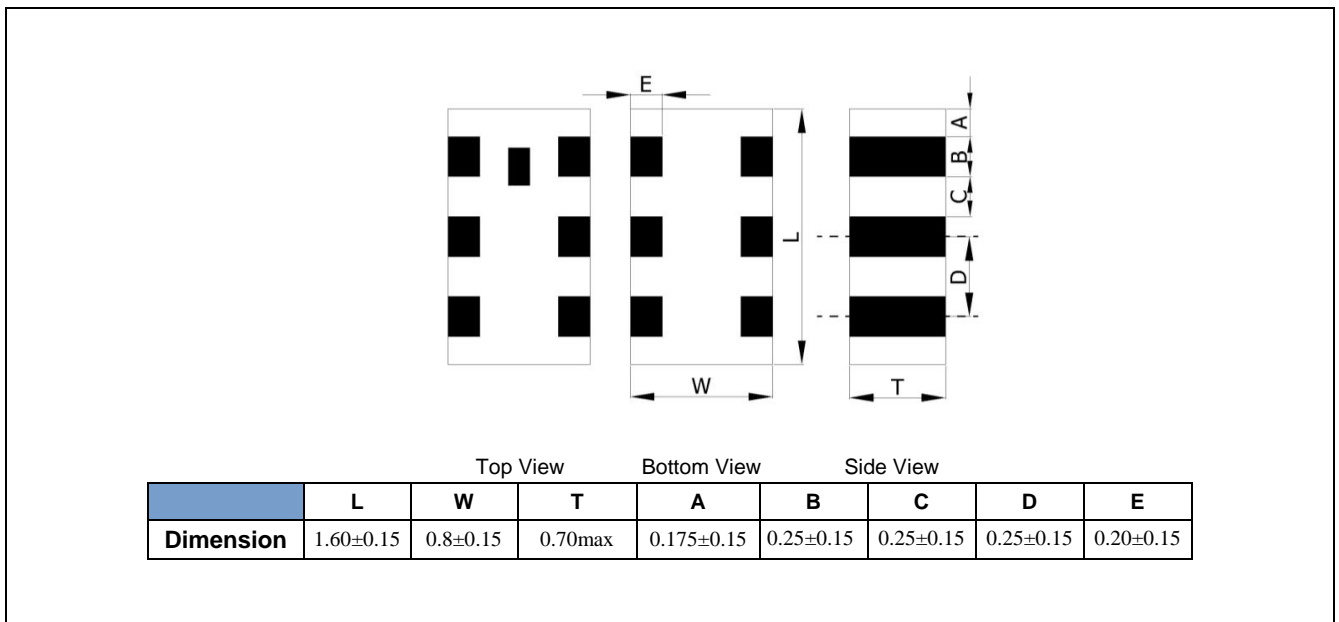


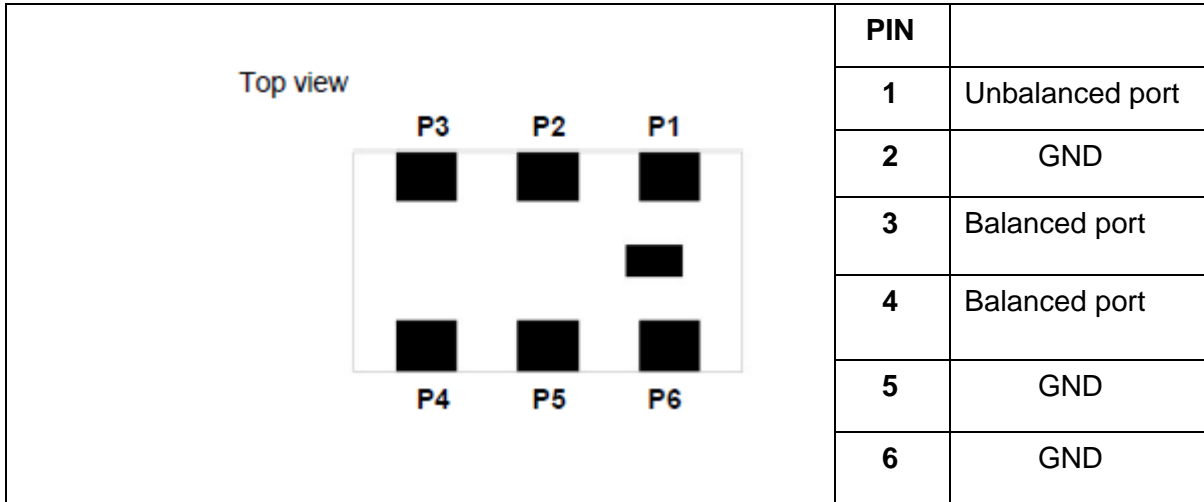
ELECTRICAL SPECIFICATION

PARAMETERS		SPECIFICATIONS	UNIT
Frequency Range		2400 ~ 2500	MHz
VSWR (max)		2.0	--
Insertion Loss, max	@ 25°C	1.75	dB
	@ -40 ~ +85 °C	1.95	dB
Unbalanced Impedance		50	Ω
Balanced Impedance		Conjugate match to TI CC253X, CC254X, CC8520 Chipset	--
Phase Difference		180 ±18	°
Amplitude Difference, max		2.3	dB
Attenuation, min	@4800 ~ 5000 MHz	19	dB
	@7200 ~ 7500 MHz	19	dB
Operating Temperature Range		-40 ~ +85	°C
Storage Temperature Range		-40 ~ +85	°C
MSL		1	-

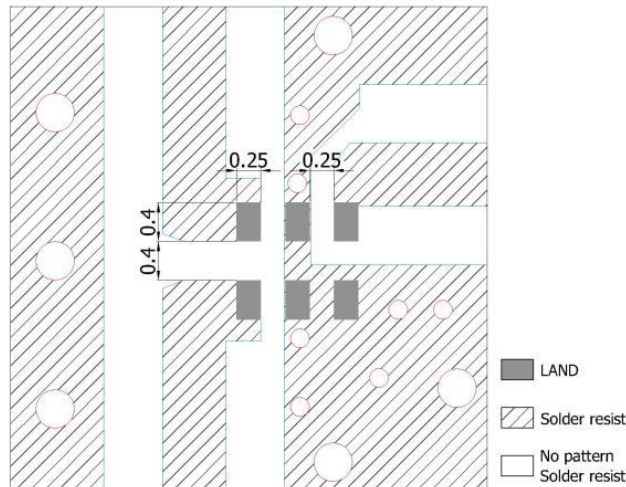
MECHANICAL SPECIFICATION



MECHANICAL SPECIFICATION (Continued)



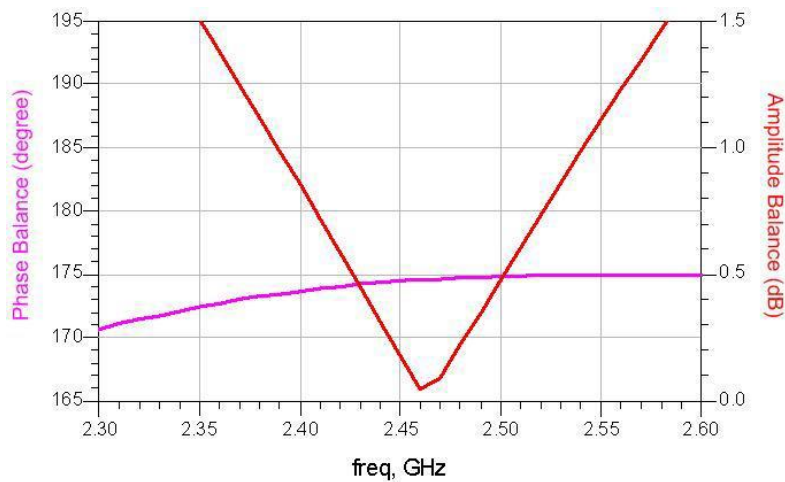
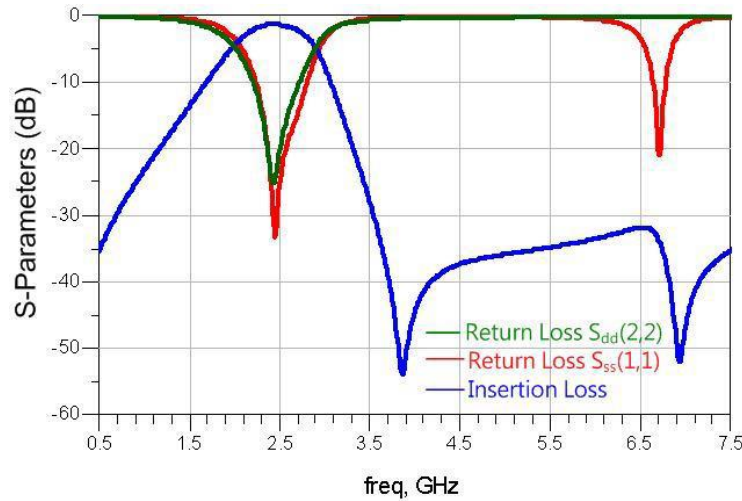
SOLDER LAND PATTERN



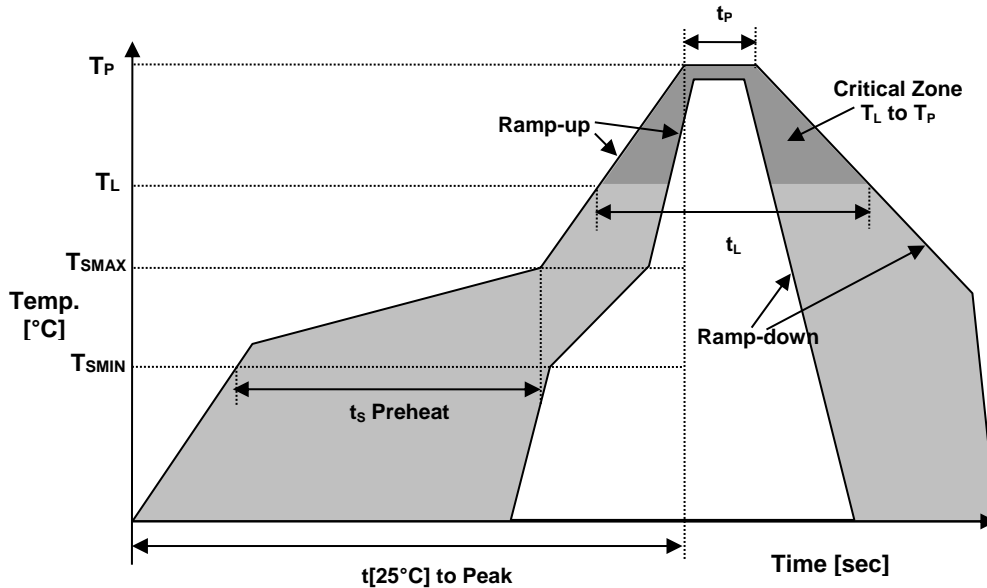
Unit : mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness.

■ ELECTRICAL CHARACTERISTICS



REFLOW PROFILE



Reflow profile		
Temperature Min Preheat	T_{SMIN}	150°C
Temperature Max Preheat	T_{SMAX}	200°C
Time (T_{SMIN} to T_{SMAX})	t_s	60-180 sec.
Temperature	T_L	217°C
Peak Temperature	T_P	260°C
Ramp-up rate	R_{UP}	3°C/sec max.
Ramp-down rate	R_{DOWN}	6°C/sec max.
Time within 5°C of Peak Temperature	t_p	10 sec.
Time $t[25^\circ\text{C}]$ to Peak Temperature	$t[25^\circ\text{C}]$ to Peak	480 sec.
Time	t_L	60-150 sec.

ENVIRONMENTAL

PARAMETER	VALUE
MOISTURE SENSITIVITY LEVEL	1
RoHS2	6/6 COMPLIANT & LEAD FREE
REACH-SVHC	COMPLIANT
HALOGEN-FREE	COMPLIANT
TERMINATION FINISH	Au



March, 2017